



Beijing Chapter's Activities, 2024
Wenjian Yu (Tsinghua Univ.)

Introduction to CEDA Beijing Chapter

Formed in Jan. 2024



Chair
Prof. Wenjian Yu
Tsinghua University



Vice Chair
Prof. Guojie Luo
Peking University



Secretary/Treasurer
Prof. Yuanqing Cheng
Beihang University

CEDA Sponsored Panel in ISEDA 2024

2.5D/3D Heterogeneous Integration: Challenges and Opportunities,
May 11 2024, Xi'an, China.

Inviting 4 professors from IME/CAS, ICT/CAS, Xidian University, HIT to be the speakers on this panel. There were more than 50 attendees at this panel.

We also promoted CEDA at this panel.

CEDA funding provides some travel grants to the organizers of this panel (one professor and one student).

The screenshot shows the program page for the panel. At the top, it says 'ISEDA 2024 International Symposium of EDA'. Below that, a blue banner reads 'PANEL'. The time is listed as 13:30-15:30 on May 11, 2024, and the venue is 2-6 / Baoji Hall. The panel title is 'P1. 2.5D/3D Heterogeneous Integration: Challenges and Opportunities' with the CEDA logo. An abstract follows, discussing Moore's Law and 2.5D/3D integration. Below the abstract, the session chair is identified as Yuanqing Cheng from Beihang University. A list of panelists is also present, with a note that each panelist will give a 10-15 minute talk.



Plan of Next CEDA-Beijing Activity

- ❖ Plan to organize 2nd Workshop of Modeling, Optimization and Simulation in VLSI EDA (MOSVIEW) in December 2024, Beihang University, Beijing, China.
- ❖ Based on organizing experiences of 1st MOSVIEW Workshop, held in December 2023, Peking University, Beijing, China. (half a day event including a dinner)
- ❖ Discuss and exchange the ideas from EDA research groups in Tsinghua Univ., Peking Univ. and Beihang Univ., and other institutes in Beijing
- ❖ We plan to invite a CEDA distinguished lecturer to this event



2nd MOSVIEW Venue



1st MOSVIEW in 2023



Thank you!